

WIRES

31.12.2010
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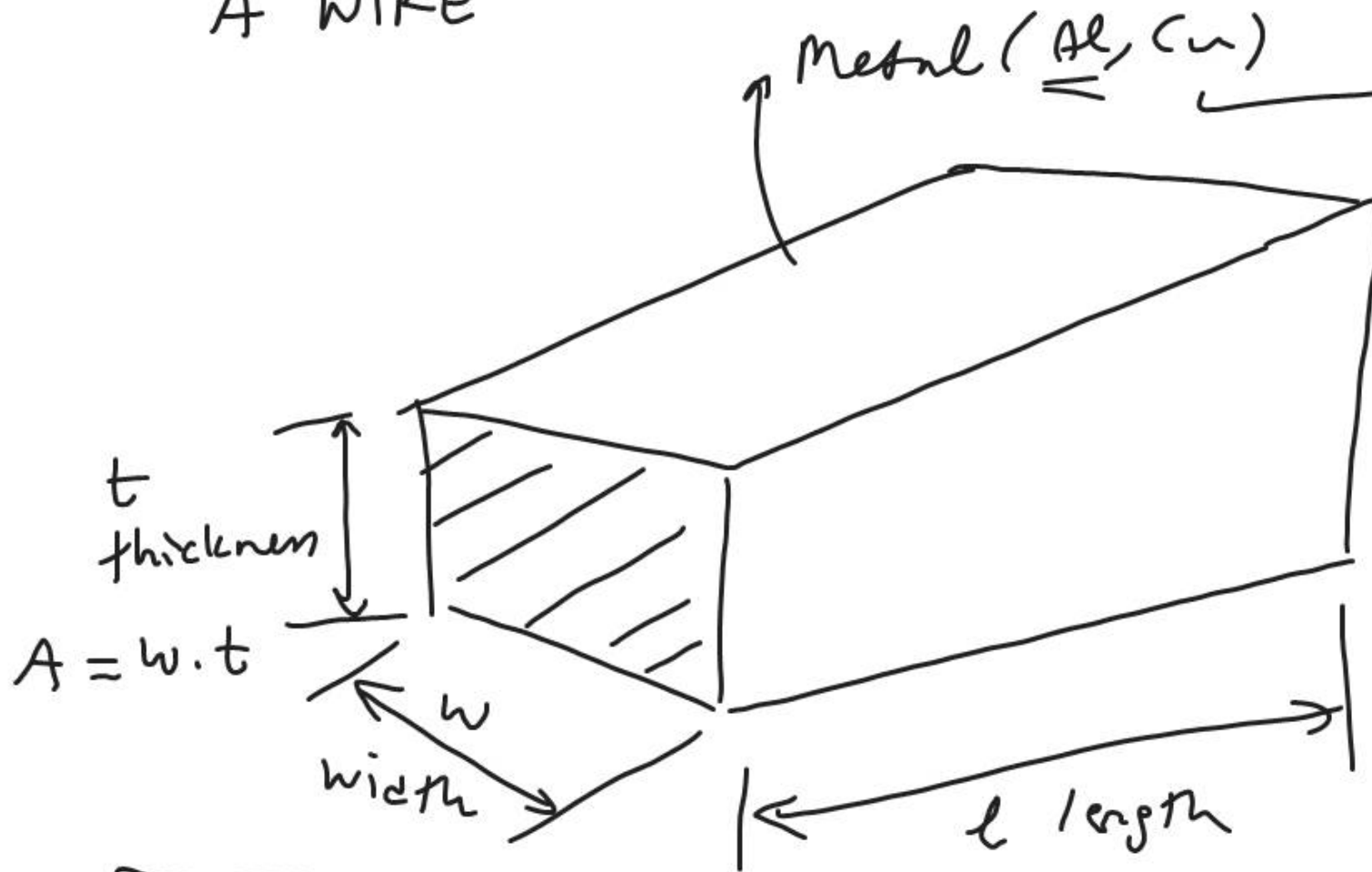
- wires in CMOS technology
- long wires getting slower over time if a DC current passes which causes the migration of metal atoms
- wire delay is a function of wire resistance and wire capacitance

$$\tau = RC$$

Ex IBM CMOS 7 Process

6 layers of Copper (Cu) wiring
1 layer of Tungsten Interconnect

A WIRE



ρ resistivity
(a material property)

The thickness
of the wire
is constant
through the
die.

$$R = \rho \cdot \frac{l}{A} = (\Omega\text{-cm}) \frac{\text{cm}}{\text{cm}^2}$$

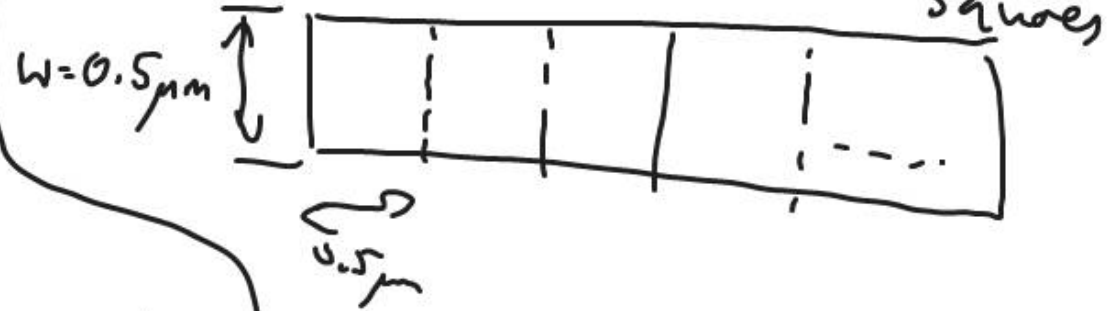
$$R = \rho \cdot \frac{l}{w \cdot t}$$

$$R = \left(\frac{\rho}{t} \right) \frac{l}{w} = \Omega \cdot \text{a number}$$

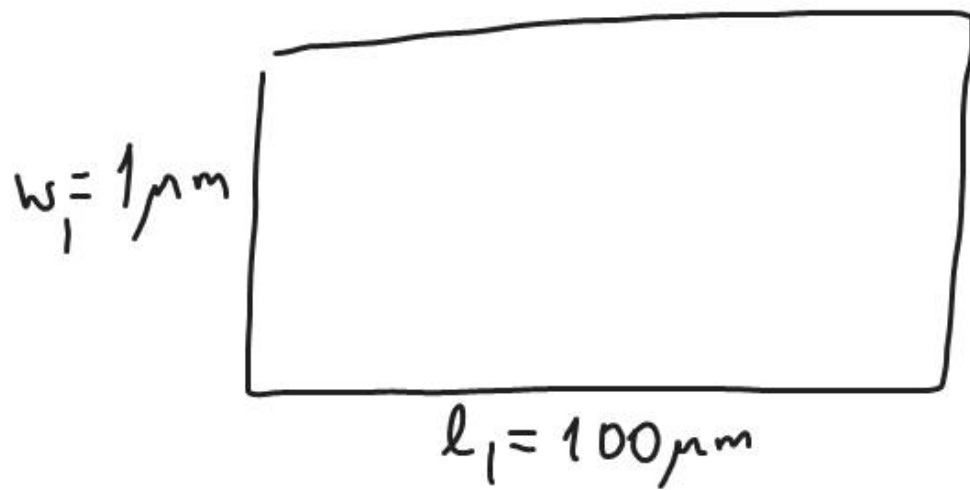
$\downarrow$
 constant for a wire
 of certain metal and
 thickness.

number of squares 10^3
 in $\frac{l}{w}$
 $\frac{l}{w} = \frac{1 \times 10^{-3}}{0.5 \times 10^{-6}} = 2000$
 squares

$$\frac{\rho}{t} = \frac{\Omega \cdot \text{cm}}{\text{cm}} = \underline{\underline{\Omega}}$$



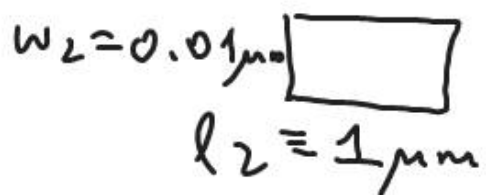
$$\frac{l}{w} = \frac{\text{cm}}{\text{cm}} = \text{unitless} \rightarrow \text{a number}$$



$$\frac{l_1}{w_1} = \frac{100 \mu m}{1 \mu m} = 100 \text{ squares}$$

$$R_1 = X \Omega \cdot 100$$

withstands more power



$$\frac{l_2}{w_2} = \frac{1 \mu m}{0.01 \mu m} = 100 \text{ squares}$$

$$R_2 = X \Omega \cdot 100$$

same resistance

Same aspect ratio ($\frac{l}{w}$)
 will give the same R (if
 they are of the same metal)

($\Omega\text{-m}$)

ρ

$$2.8 \times 10^{-8}$$

Al

$$1.7 \times 10^{-8}$$

Cu

$$1.6 \times 10^{-8}$$

Ag

TSMC

0.18 μm 6 Al metal layers

m1-5 0.08 Ω/square
 $\left(\frac{\rho}{t}\right)$

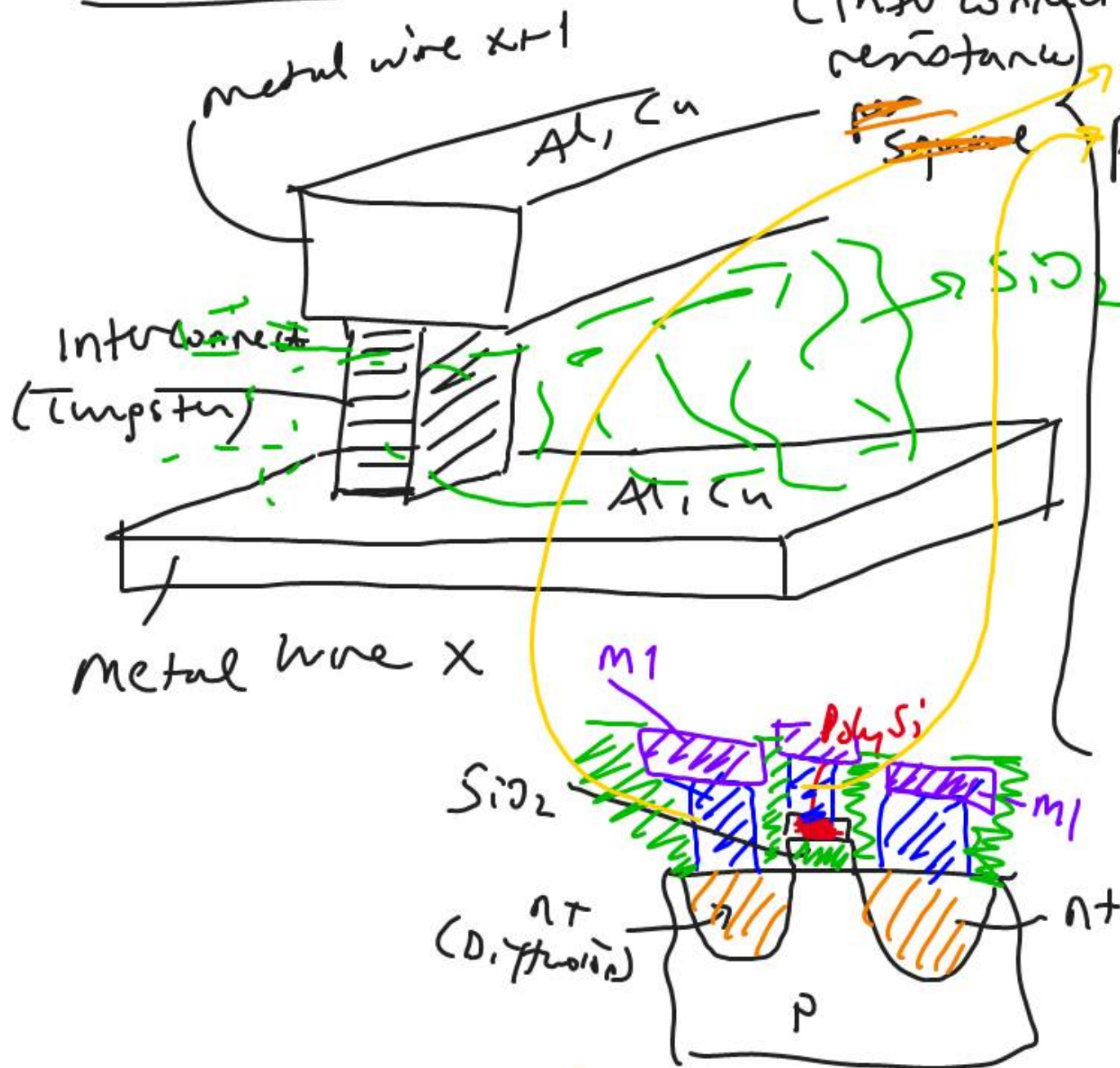
m6 0.03 Ω/square

(if we have a $1\mu\text{m} = l$, and l
 $w = 0.2\mu\text{m}$ wire of m5
 $\frac{l}{w} = \frac{1\mu\text{m}}{0.2\mu\text{m}} = 5$

$$R = \frac{0.08 \Omega}{\text{square}} \times \left(\frac{l}{w}\right) = \frac{0.08 \Omega}{\cancel{\square}} \times \cancel{5} \cancel{\square}$$
$$R = 0.4 \Omega$$

Local interconnects

TSMC 0.18 μ m 6 A1



Diff-m1: 11 Ω

Poly-m1: 10.4 Ω

M2-M1 4.5 Ω

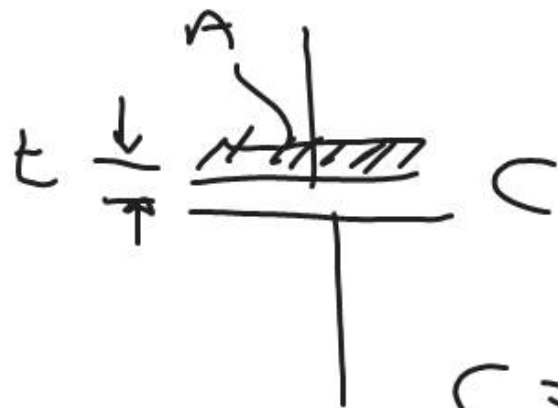
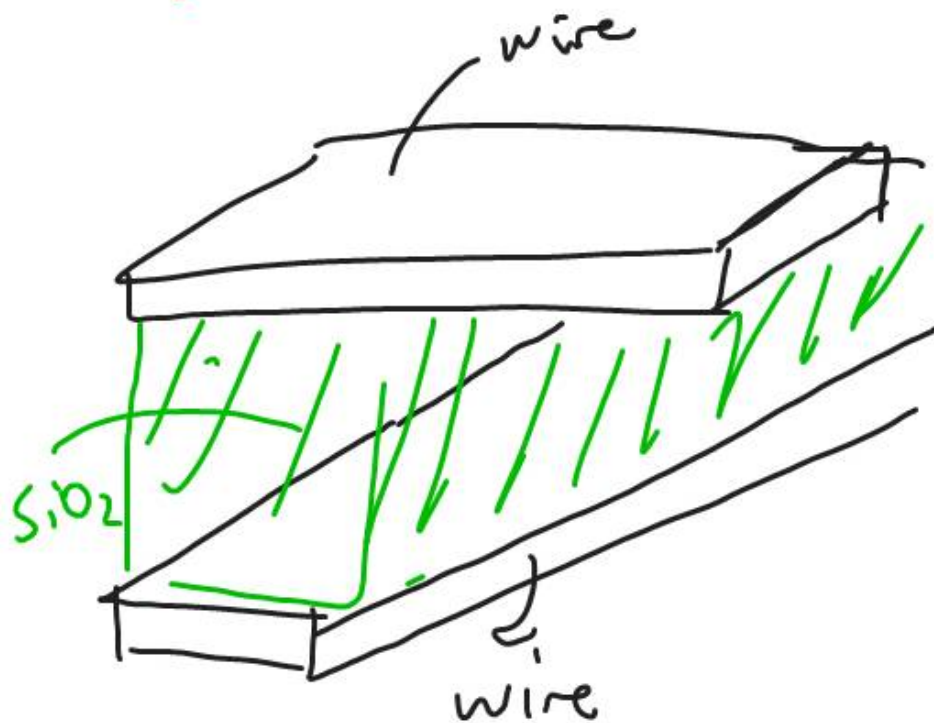
M3-M1 9.5 Ω

M4-M1 15 Ω

M5-M1 19.6 Ω

M6-M1 21.8 Ω

WIRE CAPACITANCE



$$C = \epsilon \cdot \frac{A}{t}$$

ϵ = permittivity of the material

$$\epsilon = \epsilon_0 \cdot \epsilon_r \quad \text{Absolute permittivity}$$

$$\epsilon_0 = \text{permittivity (F/m)}$$

ϵ_r = relative permittivity

	ϵ_r	$\epsilon_r = 1$ for vacuum ~ air
SiO ₂	3.9	
SiOF	3.1	
Silk Polymer	2.6	
Si	11.7	

$$C = \epsilon \frac{A}{t} = \epsilon \frac{w \cdot l}{t} \rightarrow \text{thickness of the insulator (e.g. SiO}_2\text{) between the metal layers}$$

$$\frac{C}{l} = \epsilon \left(\frac{w}{t} \right)$$



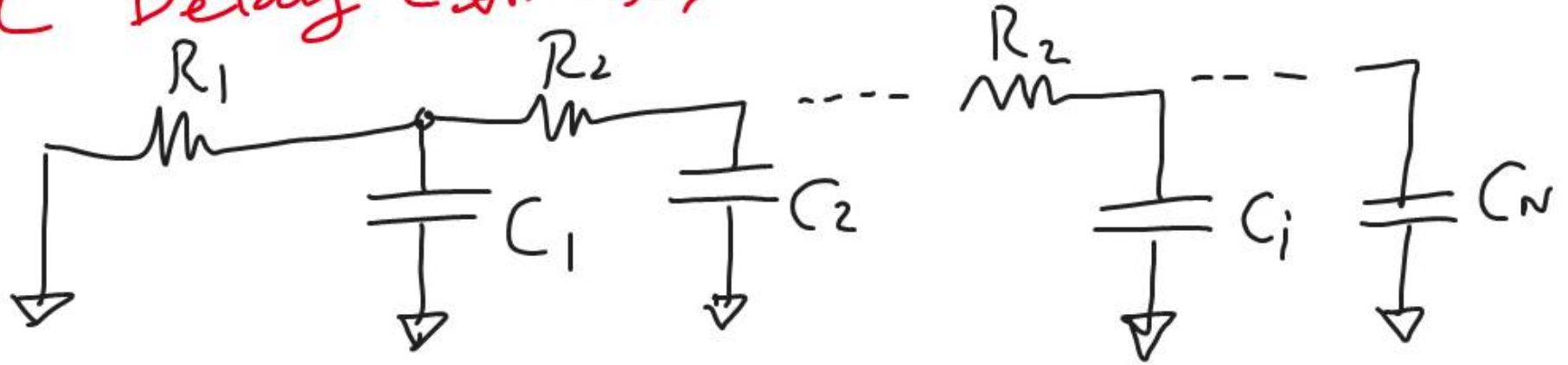
$w \cdot l = A = \text{effective area of the metal wires overlapping}$

$$\bullet 100 \text{ fF/mm} \Rightarrow$$

$$\text{femto} = 10^{-15}$$

$$\bullet 160 \text{ fF/mm}$$

RC Delay Estimator

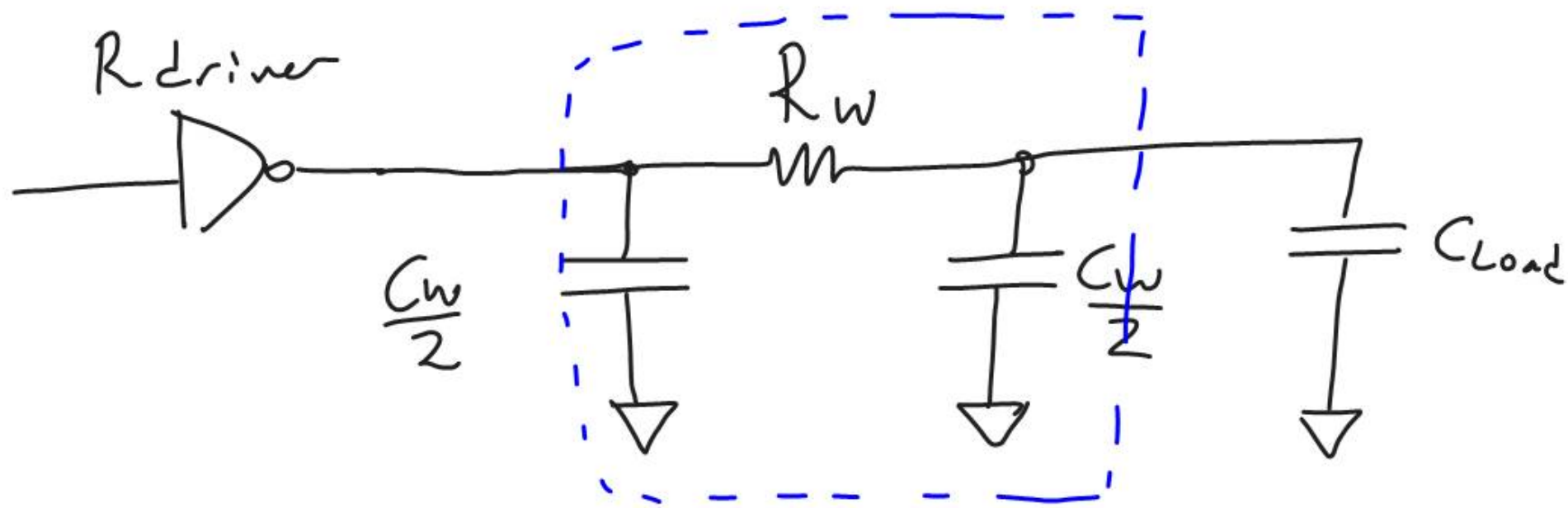


Panfield - Rubinstein Model estimates

$$\text{DELAY} = \sum_{i=1}^N \left(\sum_{j=1}^i R_j \right) C_i$$

$$N=3 \quad = R_1 C_1 + (R_1 + R_2) C_2 + (R_1 + R_2 + R_3) C_3$$

Simple Lumped- π model



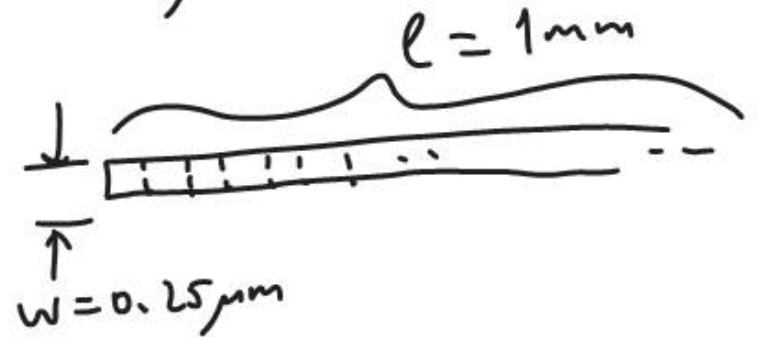
$$DELAY = R_{driver} \times \frac{C_w}{2} + (R_{driver} + R_w) \times \left(\frac{C_w}{2} + C_{load} \right)$$

example: 0.18 μ m TSMC, 5x minimums inverters
with effective resistance of 3k Ω , FO4 load (25fF)

$$\text{Delay} = R_{\text{driver}} \times C_{\text{load}} = 3\text{k}\Omega \times 25\text{fF} = 75\text{ps}$$

Now add 1mm M1 wire, 0.25μm wide

$$\rho_{\text{m1-m5}} = 0.08 \Omega/\square$$



$$\square = \frac{l}{w} = \frac{1\text{mm}}{0.25\mu\text{m}} = \frac{1\text{mm}}{0.25 \times 10^{-3}\text{mm}} = \frac{10^3}{0.25} = 4000 \square$$

$$R_{w'} = 4000 \cancel{\square} \times 0.08 \Omega / \cancel{\square} = 320 \Omega$$

$$R_{\text{vias}} = 22 \Omega$$

$$R_w = R_w' + R_{vias} = 320 + 22 = 342 \Omega$$

$$C_w = 160 \text{ fF} \quad \left(\text{remember } \frac{C}{l} = 160 \text{ fF/mm} \right)$$

$$l = 1 \text{ mm}$$

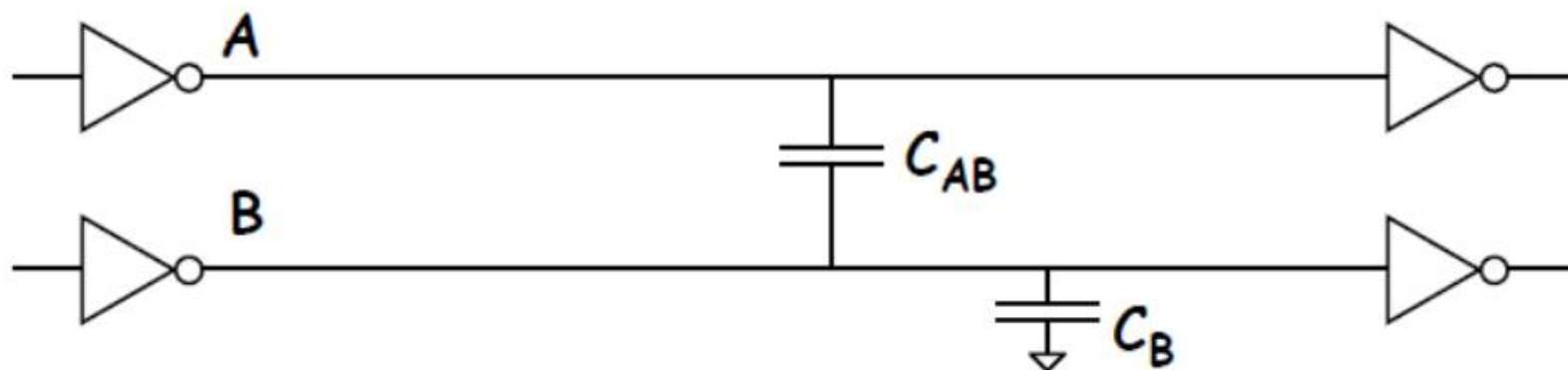
$$C = 160 \frac{\text{fF}}{\text{mm}} \times 1 \text{ mm}$$

$$\text{Delay} = R_{driver} \times \frac{C_w}{2} + \boxed{C_w = 160 \text{ fF}} \times (R_{driver} + R_w) \left(\frac{C_w}{2} + C_{load} \right)$$

$$= 3 \text{ k}\Omega \times 80 \text{ fF} + (3 \text{ k}\Omega + 342 \Omega) (80 \text{ fF} + 25 \text{ fF})$$

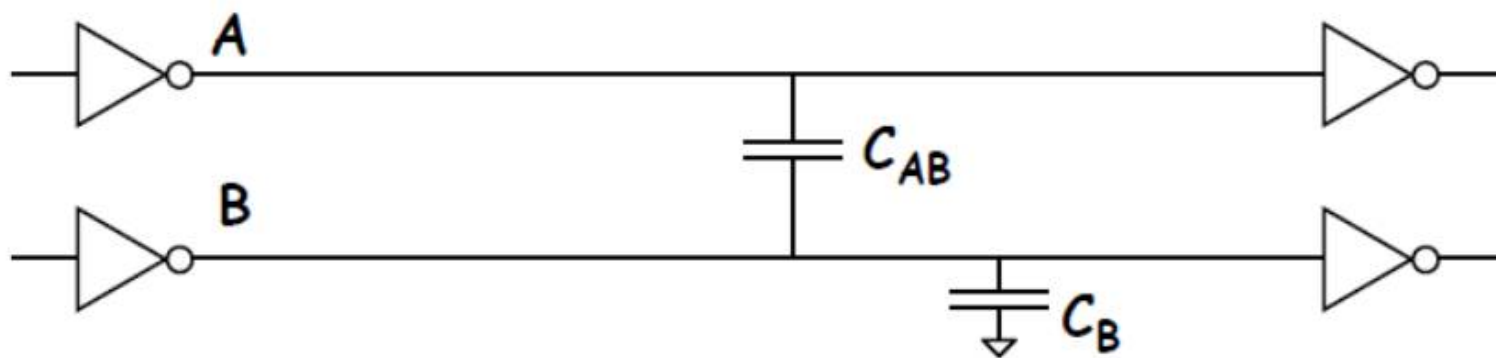
$$\text{Delay} = 591 \text{ ps} \approx 0.59 \text{ ns}$$

Coupling Capacitances



- Most capacitance is to neighboring wires
- If A switches, injects voltage noise on B
 - magnitude depends on capacitive divider formed:
$$C_{AB}/(C_{AB}+C_B)$$
- If A switches in opposite direction while B switches, coupling capacitance effectively doubles - Miller effect
- If A switches in same direction while B switches, coupling capacitance disappears
- These effects can lead to large variance in possible delay of B driver, possibly factor of 5 or 6 between best and worst case

Fixing Coupling Problems



- Avoid placing simultaneously switching signals next to each other for long parallel runs
- Reroute signals which will be quiet during switching inbetween simultaneous switching signals
- Route signals close to power rails to provide capacitance ballast
- Tough problem to solve - moving one wire can introduce new problems
 - "timing closure" causes many real-world schedule slips